

ABSTRACT

HEAT-RESISTANT PHOTSENSITIVE RESIN COMPOSITION, PROCESS
FOR PRODUCING PATTERN FROM THE COMPOSITION, AND
5 ELECTRONIC PART

A heat-resistant photosensitive resin composition
which comprises (A) a polymer having an acidic
functional group and/or a substituent derived therefrom,
10 (B) a compound having at least one substituent derived
from an amine-derived functional group, (C) a
photoreactive compound, and (D) a solvent. Due to this
constitution, the composition gives a cured film having
satisfactory properties. A pattern having satisfactory
15 resolution can be produced from this photosensitive
resin composition, and a high-quality electronic part
can be provided with the pattern.

Figure 1